



Material Composition Declaration

EPC2053

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/19/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	10.7294	84.1858	86.4283	841858
	Silicon oxide	7631-86-9	0.0435	0.3411		3411
	Silicon nitride	12033-89-5	0.0202	0.1585		1585
	Gallium nitride	25617-97-4	0.0381	0.2988		2988
	Aluminum	7429-90-5	0.0794	0.6231		6231
	Aluminum nitride	24304-00-5	0.0086	0.0679		679
	Titanium	7440-32-6	0.0016	0.0123		123
	Titanium nitride	25583-20-4	0.0082	0.0647		647
	Copper	7440-50-8	0.0026	0.0208		208
	Tungsten	7440-33-7	0.0034	0.0264		264
	Polyimide		0.0802	0.6290		6290
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0079	0.2060	79
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0252	0.1981		1981
Solder Bump	Tin	7440-31-5	1.6268	12.7643	13.3657	127643
	Silver	7440-22-4	0.0681	0.5346		5346
	Copper	7440-50-8	0.0085	0.0668		668
Sum in total:			12.7449	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.